

DEVELOPMENT OF LARGE SCALE CMB DETECTOR ARRAYS AT ARGONNE



Photo: Joshua Montgomery

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SPT COLLABORATION

- Argonne
- Case Western Reserve University
- Fermi National Acceleratory Lab
- Harvard-Smithsonian Astrophysical Observatory
- McGill University
- LBNL / University of California, Berkeley
- University of California, Davis
- University of Chicago
- University of Colorado at Boulder
- University of Illinois Urbana-Champaign
- University of Toronto



OUTLINE

- Motivation
- CMB Detector Arrays
- Detector Array Fabrication
- Future Developments Moving towards CMB-S4



COSMIC MICROWAVE BACKGROUND

CMB Science



- Temperature variations tell us about distribution of matter in the universe
- E-mode (curl free) polarization from density perturbations
- B-mode (divergence free) polarization from lensed E-modes and gravitational waves
- Science products
 - scalar-to-tensor ratio, r
 - effective number of relativistic species, ΔNeff
 - sum of neutrino masses, Σm_v



COSMIC MICROWAVE BACKGROUND

CMB Experimental Scaling

- Detectors in ground-based experiments are already mostly backgroundlimited (largest noise source is photon noise from the sky)
- Measurements of B-modes requires increasingly sensitive experiments
- More sensitivity = More detectors



COSMIC MICROWAVE BACKGROUND

CMB-S4

- Single experiment bringing together the CMB community
 - Two sites: South Pole and Atacama
 - Both small (0.5 m) and large (6 m) aperture telescopes
- ~ 510K detectors in 9 frequency bands
 - TES detectors
 - Feedhorn coupling
 - Dual-polarization, dichroic pixels
- Community fabrication effort with detectors made at several sites (ANL, LBNL/SeeQc, SLAC, others....)

SAT receivers

18 SATs with a total of 153,232 detectors

	LF	CF _{low}	CF_{high}	HF
Center frequency (GHz)	30/40	85/145	95/155	220/270
Primary lens diam. (cm)	55	55	55	44
FWHM (arcmin)	72.8	25.5	22.7	13
Fractional bandwidth	0.3	0.24	0.24	0.22
NET ($\mu K \sqrt{s}$) per detector	177/224	270/238	309/331	747/1281
N _{det} per optics tube	288	3524	3524	8438
Number of optics tubes	2	6	6	4
Number of detectors	576/576	21,144/21,144	21,144/21,144	33,752/33,752

LAT receivers

3 LATS with a total of 357,952 detectors

	ULF	LF	MF	HF
Center frequency (GHz)	20	27/39	93/145	225/278
FWHM (arcmin)	10.0	7.4/5.1	2.2/1.4	1.0/0.9
Fractional bandwidth	0.25	0.22/0.46	0.38/0.28	0.27/0.16
NET ($\mu K \sqrt{s}$) per detector	438	383/250	302/356	737/1840
N _{det} per optics tube	160	320/320	3460/3460	3744/3744
N_{tubes} wide survey (2 LATs)	0	2	12	5
N _{tubes} delensing (1 LAT)	1	2	12	4
Number of detectors	576/576	21,144/21,144	21,144/21,144	33,752/33,752

CMB-S4 Science Case, Reference Design, and Project Plan; arXiv:1907.04473



CMB DETECTOR ARRAYS

Transition Edge Sensors (TES)

- Most commonly used detector in current CMB experiments
- Superconducting Thermistor
- Voltage bias in the middle of superconducting – normal transition
 - Negative ETF stabilizes bias points and speeds up detector response
 - Can be DC or AC biased
- SQUID amplifier based readout
 - Time Domain Mux (TDM)
 - Frequency Domain Mux (FDM)
- Noise levels sub-dominate to other noise sources (e.g. readout and sky)



0.9



CMB DETECTOR ARRAYS

SPT stages



Detector Design

- Science drivers
 - Frequency Bands
 - Saturation Powers
 - Noise levels
- Practical Drivers
 - Cryostat base temperature
 - Telescope optics
 - Readout system
- Need control over detector parameters
 - T_C
 - Rn
 - G
- Depending on design, parameters are degenerate

Constraints on $T_{\rm c}$ and $R_{\rm N}$



F.W. Carter, et. al. in J. Low Temp. Phys. 1 (2018).



Pixel Layout

- 6 TES per pixel
 - Dual polarization
 - Tri-chroic (95, 150, and 220 GHz)
- Key components
 - Broadband sinuous antenna
 - In pixel channelizing
 - Microwave crossovers
- 271 pixels on a 6" wafer (1626 TES per wafer)
- 17 Step Fabrication process
- Batch of 5 wafers takes ~ 1 month to produce



C.M. Posada, et.al. in Supercond. Sci. Technol. 28, 1 (2015).



T_C Engineering

- Ti/Au/Ti/Au Quadlayer
 - Base Ti helps adhesion
 - Both Au layers help to suppress T_C
 - Top Au layer limits oxidation of the Ti
- Control T_C using layer thickness
- Control R_n using TES width
- Material properties can very with each new sputtering target



¹¹ F.W. Carter, et. al. in J. Low Temp. Phys. 1 (2018).

'G' Engineering

- G is a function of leg geometry and material parameters
- G is determined from measurements of detector saturation power vs temperature
 - $P_{sat} = G^{*}(T^{n}-T^{n}_{bath}) / nT^{n-1}$
- Measurements confirm that:
 - Conductance scales as leg width / length for constant thickness
 - Microstrip dielectric has major impact on G





J. Ding, et.al. in IEEE Trans. Appl. Supercond. 27, 1 (2017).



SPT-3G Array Performance

Detectors are as good as one can get!

- Detector noise dominated by fluctuations of absorbed photons **oolometers**
 - measured on sky
 - NO GAIN from lower noise detectors
- Array mapping speed
 - 9 / 7.5 / 30 μ K \sqrt{s} in 90 / 150 / 220 GHz





Number of pairs of difference map added



220GHz T map - Noise in the running coadded maps (excluded maps: {el 0: 1, el 1: 0, el 2: 2, el 3: 0})



Number of pairs of difference map added



Number of pairs of difference map added

MOVING TOWARDS CMB-S4 Fabrication Facilities



17,500 sq. ft. - Class 100-1000 - Bay-and-chase design

MOVING TOWARDS CMB-S4

AIMn TES: Doping with magnetic materials

- Control Tc by doping Al with Mn.
- Fine tune Tc with post deposition bake



Demonstrated control of TES Tc in range 130-450mK

D. Li *et al., J. Low Temp. Phys.*, vol. 184, no. 1–2, pp. 66–73, Jul. 2016.
A. J. Anderson *et al., J. Low Temp. Phys.*, Nov. 2019.

AIMn TES deployed on SPT-3G in 2018



Distribution of normal resistance (left) and Tc (right) measured in the field



 $\label{eq:constraint} \begin{array}{l} \mbox{Resistance as a function of temperature for AlMn(200 nm, 2000ppm)\Ti(15nm)\Au(15nm) films with T_C of ~ 140 mK. The TES are 10 um long by 80 um (140 um) wide for the red (black) data. \end{array}$



MOVING TOWARDS CMB-S4 OMT Fabrication

- OMT likely to be used on several bands for CMB-S4
- OMT fabrication requires silicon deep reactive ion etcher (DRIE)
 - PlasmaTherm DRIE installed at CNM in July 2019



90 GHz OMT probes in SPT3G layout

SiN membranes created by DRIE



MOVING TOWARDS CMB-S4

MKIDS

- Could significantly reduce number of optics tubes needed for higher frequency bands
- Fabrication of first released devices (220/270 GHz) now completed







FINAL THOUGHTS

- Advances in detector arrays have enabled new CMB Science
- Making/using large detector arrays is hard
- Argonne successfully fabrication and deployed the SPT-3G focal plane
- We are developing the necessary processes for CMB-S4 compliant detectors
- Effort from the entire community will be required to deploy CMB-S4



THANK YOU



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